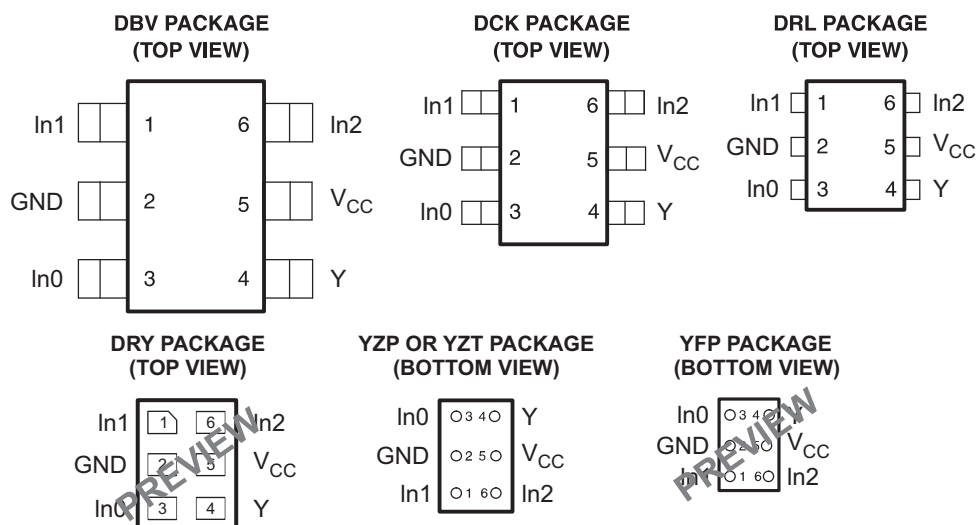


FEATURES

- Available in the Texas Instruments NanoFree™ Packages
- Low Static-Power Consumption ($I_{CC} = 0.9 \mu A$ Max)
- Low Dynamic-Power Consumption ($C_{pd} = 4.6$ pF Typ at 3.3 V)
- Low Input Capacitance ($C_i = 1.5$ pF Typ)
- Low Noise – Overshoot and Undershoot <10% of V_{CC}
- I_{off} Supports Partial-Power-Down Mode Operation
- Includes Schmitt-Trigger Inputs
- Wide Operating V_{CC} Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $t_{pd} = 5.5$ ns Max at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- ESD Protection Exceeds ± 5000 V With Human-Body Model



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static and dynamic power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity, which produces very low undershoot and overshoot characteristics.

The SN74AUP1G58 features configurable multiple functions. The output state is determined by eight patterns of 3-bit input. The user can choose the logic functions AND, OR, NAND, NOR, XNOR, inverter, and noninverter. All inputs can be connected to V_{CC} or GND.

The device functions as an independent gate with Schmitt-trigger inputs, which allow for slow input transition and better switching noise immunity at the input.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

SN74AUP1G58

LOW-POWER CONFIGURABLE MULTIPLE-FUNCTION GATE

SCES504H–NOVEMBER 2003–REVISED DECEMBER 2007

DESCRIPTION/ORDERING INFORMATION

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

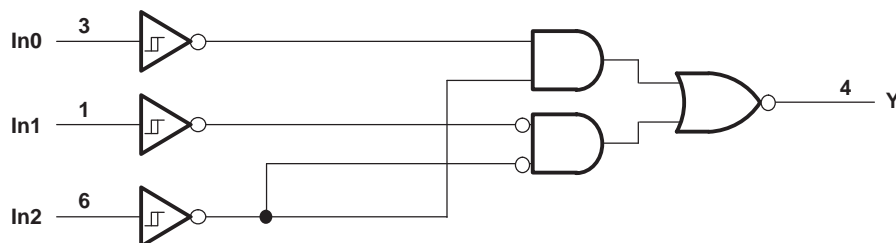
T_A	PACKAGE ⁽¹⁾⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾
–40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YFP (Pb-free)	Reel of 3000	SN74AUP1G58YFPR	PREVIEW
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74AUP1G58YZPR	_ _ _HJ_
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZT (Pb-free)	Reel of 3000	SN74AUP1G58YZTR	_ _ _HJ_
	SON – DRY	Reel of 5000	SN74AUP1G58DRYR	PREVIEW
	SOT (SOT-23) – DBV	Reel of 3000	SN74AUP1G58DBVR	H58_
	SOT (SC-70) – DCK	Reel of 3000	SN74AUP1G58DCKR	HJ_
	SOT (SOT-553) – DRL	Reel of 4000	SN74AUP1G58DRLR	

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (3) DBV/DCK/DRL/DRY: The actual top-side marking has one additional character that designates the assembly/test site.
YFP/YZP/YZT: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

FUNCTION TABLE

INPUTS			OUTPUT Y
In2	In1	In0	
L	L	L	L
L	L	H	H
L	H	L	L
L	H	H	H
H	L	L	H
H	L	H	H
H	H	L	L
H	H	H	L

LOGIC DIAGRAM (POSITIVE LOGIC)



FUNCTION SELECTION TABLE

LOGIC FUNCTION	FIGURE NO.
2-input AND with inverted input	2, 3
2-input NAND	1
2-input NAND with both inputs inverted	4
2-input OR	4
2-input OR with both inputs inverted	1
2-input NOR with inverted input	2, 3
2-input XOR	5

LOGIC CONFIGURATIONS

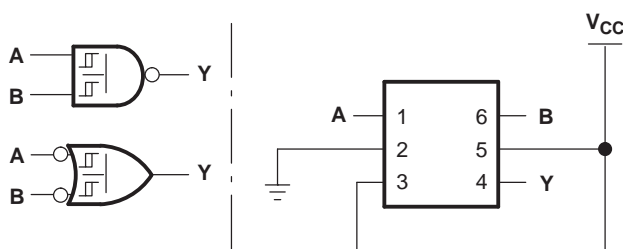


Figure 1. 2-Input NAND Gate

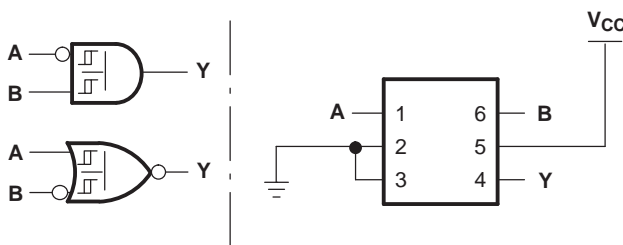


Figure 2. 2-Input AND Gate With Inverted A Input

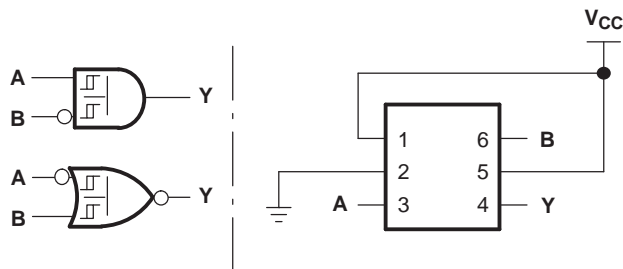


Figure 3. 2-Input AND Gate With Inverted B Input

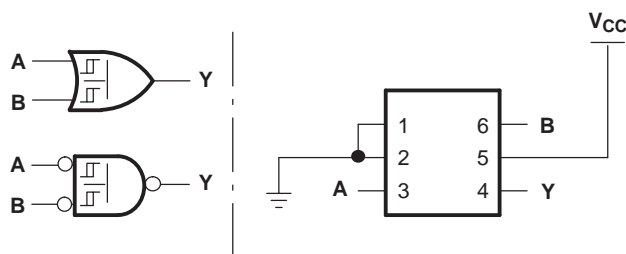


Figure 4. 2-Input OR Gate

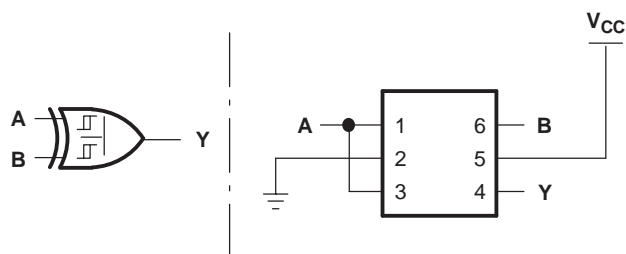


Figure 5. 2-Input XOR Gate

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	4.6	V
V_I	Input voltage range ⁽²⁾		–0.5	4.6	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾		–0.5	4.6	V
V_O	Output voltage range in the high or low state ⁽²⁾		–0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		–50	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	mA
I_O	Continuous output current			±20	mA
	Continuous current through V_{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance ⁽³⁾	DBV package		165	°C/W
		DCK package		259	
		DRL package		142	
		DRY package		234	
		YFP/YZP/YZT package		123	
T_{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		0.8	3.6	V
V_I	Input voltage		0	3.6	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 0.8\text{ V}$		–20	μA
		$V_{CC} = 1.1\text{ V}$		–1.1	mA
		$V_{CC} = 1.4\text{ V}$		–1.7	
		$V_{CC} = 1.65\text{ V}$		–1.9	
		$V_{CC} = 2.3\text{ V}$		–3.1	
		$V_{CC} = 3\text{ V}$		–4	
I_{OL}	Low-level output current	$V_{CC} = 0.8\text{ V}$		20	μA
		$V_{CC} = 1.1\text{ V}$		1.1	mA
		$V_{CC} = 1.4\text{ V}$		1.7	
		$V_{CC} = 1.65\text{ V}$		1.9	
		$V_{CC} = 2.3\text{ V}$		3.1	
		$V_{CC} = 3\text{ V}$		4	
T_A	Operating free-air temperature		–40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74AUP1G58

LOW-POWER CONFIGURABLE MULTIPLE-FUNCTION GATE

SCES504H–NOVEMBER 2003–REVISED DECEMBER 2007

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARMETER		TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V _{T+} Positive-going input threshold voltage		0.8 V	0.3		0.6	0.3	0.6	V	
		1.1 V	0.53		0.9	0.53	0.9		
		1.4 V	0.74		1.11	0.74	1.11		
		1.65 V	0.91		1.29	0.91	1.29		
		2.3 V	1.37		1.77	1.37	1.77		
		3 V	1.88		2.29	1.88	2.29		
V _{T–} Negative-going input threshold voltage		0.8 V	0.1		0.6	0.1	0.6	V	
		1.1 V	0.26		0.65	0.26	0.65		
		1.4 V	0.39		0.75	0.39	0.75		
		1.65 V	0.47		0.84	0.47	0.84		
		2.3 V	0.69		1.04	0.69	1.04		
		3 V	0.88		1.24	0.88	1.24		
ΔV _T Hysteresis (V _{T+} – V _{T–})		0.8 V	0.07		0.5	0.07	0.5	V	
		1.1 V	0.08		0.46	0.08	0.46		
		1.4 V	0.18		0.56	0.18	0.56		
		1.65 V	0.27		0.66	0.27	0.66		
		2.3 V	0.53		0.92	0.53	0.92		
		3 V	0.79		1.31	0.79	1.31		
V _{OH}	I _{OH} = –20 μA	0.8 V to 3.6 V	V _{CC} – 0.1			V _{CC} – 0.1		V	
	I _{OH} = –1.1 mA	1.1 V	0.75 × V _{CC}			0.7 × V _{CC}			
	I _{OH} = –1.7 mA	1.4 V	1.11			1.03			
	I _{OH} = –1.9 mA	1.65 V	1.32			1.3			
	I _{OH} = –2.3 mA	2.3 V	2.05			1.97			
	I _{OH} = –3.1 mA		1.9			1.85			
	I _{OH} = –2.7 mA	3 V	2.72			2.67			
	I _{OH} = –4 mA		2.6			2.55			
V _{OL}	I _{OL} = 20 μA	0.8 V to 3.6 V	0.1			0.1		V	
	I _{OL} = 1.1 mA	1.1 V	0.3 × V _{CC}			0.3 × V _{CC}			
	I _{OL} = 1.7 mA	1.4 V	0.31			0.37			
	I _{OL} = 1.9 mA	1.65 V	0.31			0.35			
	I _{OL} = 2.3 mA	2.3 V	0.31			0.33			
	I _{OL} = 3.1 mA		0.44			0.45			
	I _{OL} = 2.7 mA	3 V	0.31			0.33			
	I _{OL} = 4 mA		0.44			0.45			
I _I	All inputs	V _I = GND to 3.6 V	0 V to 3.6 V			0.1		0.5	μA
I _{off}		V _I or V _O = 0 V to 3.6 V	0 V			0.2		0.6	μA
ΔI _{off}		V _I or V _O = 0 V to 3.6 V	0 V to 0.2 V			0.2		0.6	μA
I _{CC}		V _I = GND or (V _{CC} to 3.6 V), I _O = 0	0.8 V to 3.6 V			0.5		0.9	μA
ΔI _{CC}		V _I = V _{CC} – 0.6 V ⁽¹⁾ , I _O = 0	3.3 V			40		50	μA
C _i		V _I = V _{CC} or GND	0 V	1.5					pF
			3.6 V	1.5					
C _O		V _O = GND	0 V			3			pF

(1) One input at V_{CC} – 0.6 V, other inputs at V_{CC} or GND

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 5$ pF (unless otherwise noted) (see Figure 6 and Figure 7)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	In0, In1, or In2	Y	0.8 V		23.6				ns
			1.2 V \pm 0.1 V	2.8	9.4	13.8	2.3	17.4	
			1.5 V \pm 0.1 V	2.1	6.5	9.2	1.6	11.3	
			1.8 V \pm 0.15 V	1.5	5.4	7.4	1	9	
			2.5 V \pm 0.2 V	1.1	4	5.6	0.6	6.6	
			3.3 V \pm 0.3 V	1	3.2	4.6	0.5	5.5	

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 10$ pF (unless otherwise noted) (see Figure 6 and Figure 7)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	In0, In1, or In2	Y	0.8 V		26.4				ns
			1.2 V \pm 0.1 V	3.2	10.7	15.2	2.7	19	
			1.5 V \pm 0.1 V	2	7.5	10.5	1.5	12.5	
			1.8 V \pm 0.15 V	1.1	6.2	8.4	0.6	10.2	
			2.5 V \pm 0.2 V	1	4.6	6.4	0.5	7.6	
			3.3 V \pm 0.3 V	1	3.7	5.3	0.5	6.3	

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 15$ pF (unless otherwise noted) (see Figure 6 and Figure 7)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	In0, In1, or In2	Y	0.8 V		29.6				ns
			1.2 V \pm 0.1 V	3.8	11.8	16.8	3.3	21.1	
			1.5 V \pm 0.1 V	2.9	8.3	11.6	2.4	13.8	
			1.8 V \pm 0.15 V	2.2	6.8	9.3	1.7	11.3	
			2.5 V \pm 0.2 V	1.7	5.1	7	1.2	8.4	
			3.3 V \pm 0.3 V	1.4	4.2	5.9	0.9	7	

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 30$ pF (unless otherwise noted) (see Figure 6 and Figure 7)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	In0, In1, or In2	Y	0.8 V		38.1				ns
			1.2 V \pm 0.1 V	5.1	15	21.4	4.6	26.6	
			1.5 V \pm 0.1 V	4	10.6	14.6	3.5	17.4	
			1.8 V \pm 0.15 V	3.2	8.7	11.7	2.7	14.2	
			2.5 V \pm 0.2 V	2.5	6.5	8.7	2	10.5	
			3.3 V \pm 0.3 V	2.1	5.4	7.3	1.6	8.7	

SN74AUP1G58

LOW-POWER CONFIGURABLE MULTIPLE-FUNCTION GATE

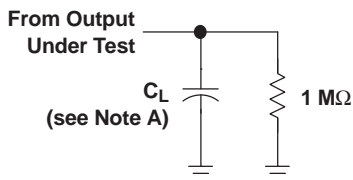
SCES504H–NOVEMBER 2003–REVISED DECEMBER 2007

Operating Characteristics

$T_A = 25^\circ\text{C}$

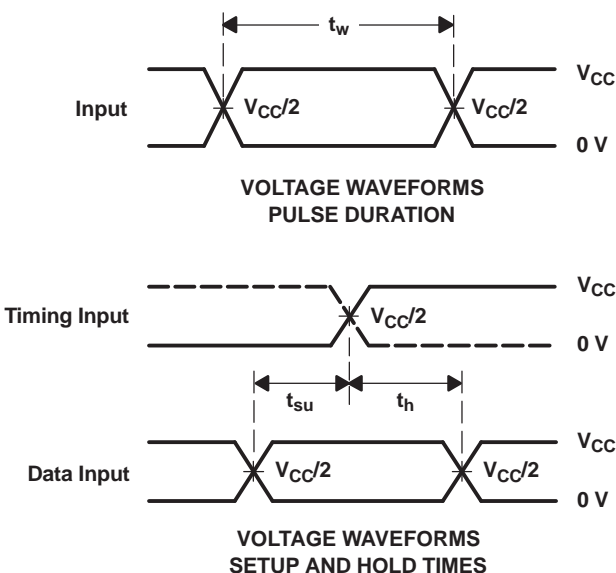
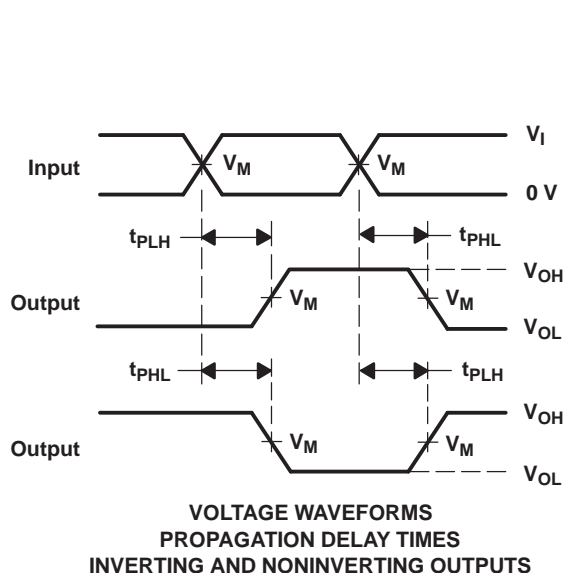
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$f = 10\text{ MHz}$	0.8 V	4	pF
			1.2 V \pm 0.1 V	4	
			1.5 V \pm 0.1 V	4	
			1.8 V \pm 0.15 V	4	
			2.5 V \pm 0.2 V	4.3	
			3.3 V \pm 0.3 V	4.6	

PARAMETER MEASUREMENT INFORMATION
(Propagation Delays, Setup-and-Hold Times, and Pulse Duration)



LOAD CIRCUIT

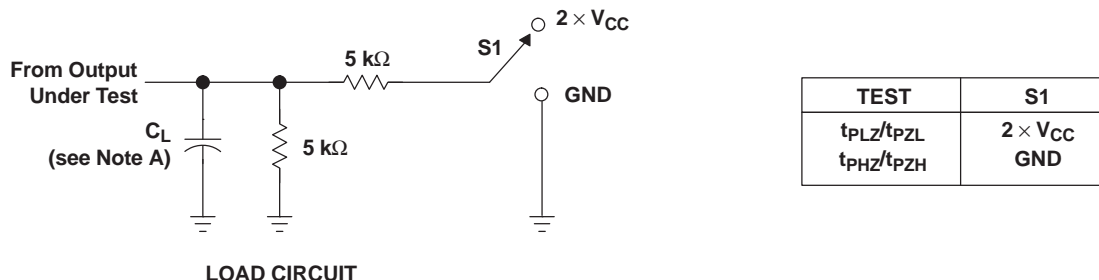
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



- NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, slew rate $\geq 1 \text{ V/ns}$.
C. The outputs are measured one at a time, with one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd} .
E. All parameters and waveforms are not applicable to all devices.

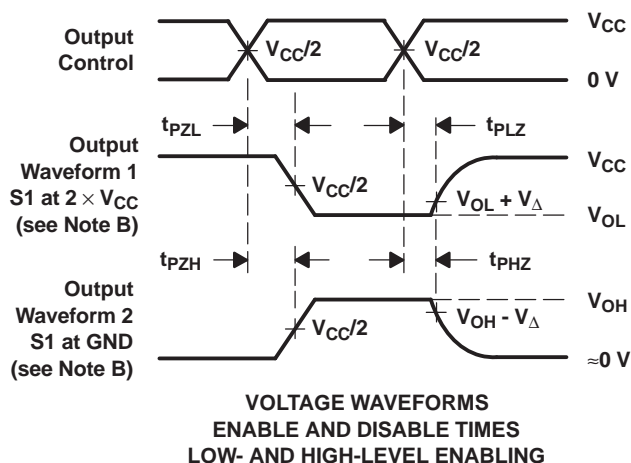
Figure 6. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (Enable and Disable Times)



LOAD CIRCUIT

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_{Δ}	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, slew rate $\geq 1 \text{ V/ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. All parameters and waveforms are not applicable to all devices.

Figure 7. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AUP1G58DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DBVRE4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DBVTE4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DCKTE4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DCKTG4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DRLR	ACTIVE	SOT	DRL	6	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58DRLRG4	ACTIVE	SOT	DRL	6	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G58YZPR	ACTIVE	DSBGA	YZP	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

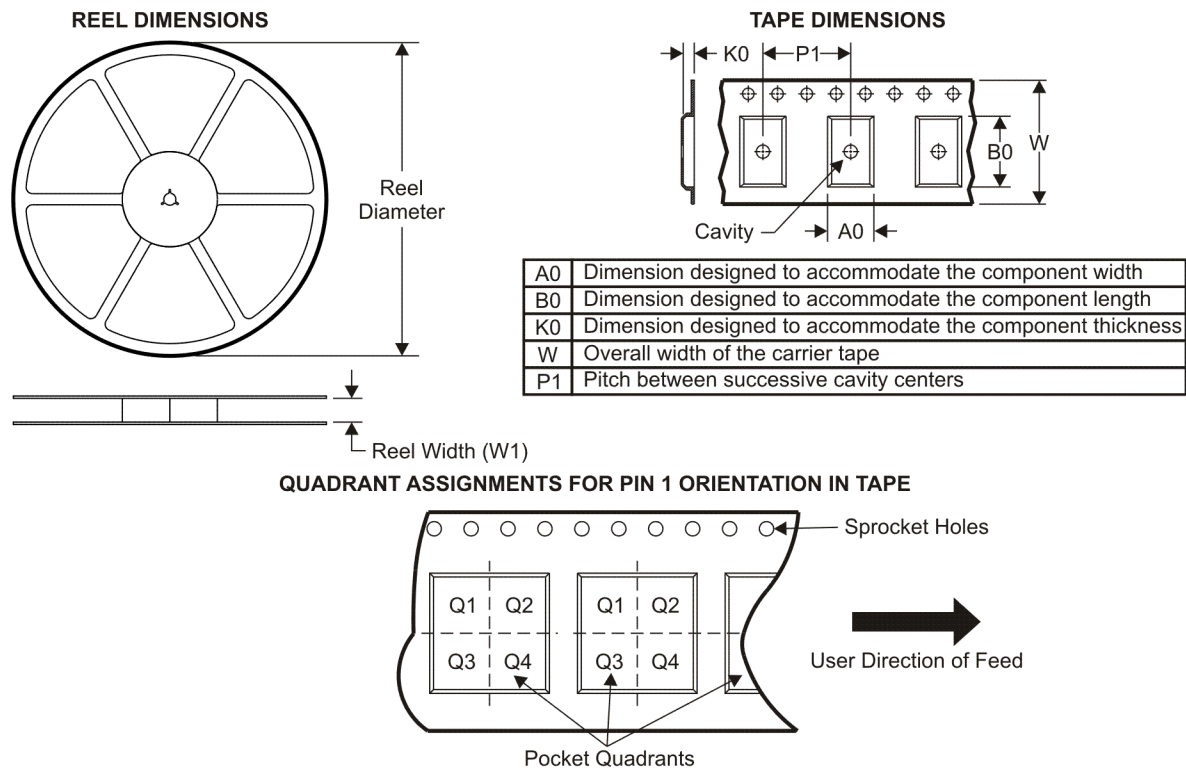
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G58DBVR	SOT-23	DBV	6	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AUP1G58DBVT	SOT-23	DBV	6	250	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74AUP1G58DCKR	SC70	DCK	6	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AUP1G58DCKT	SC70	DCK	6	250	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74AUP1G58DRLR	SOT	DRL	6	4000	180.0	9.2	1.78	1.78	0.69	4.0	8.0	Q3
SN74AUP1G58YZPR	DSBGA	YZP	6	3000	180.0	8.4	1.02	1.52	0.66	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS

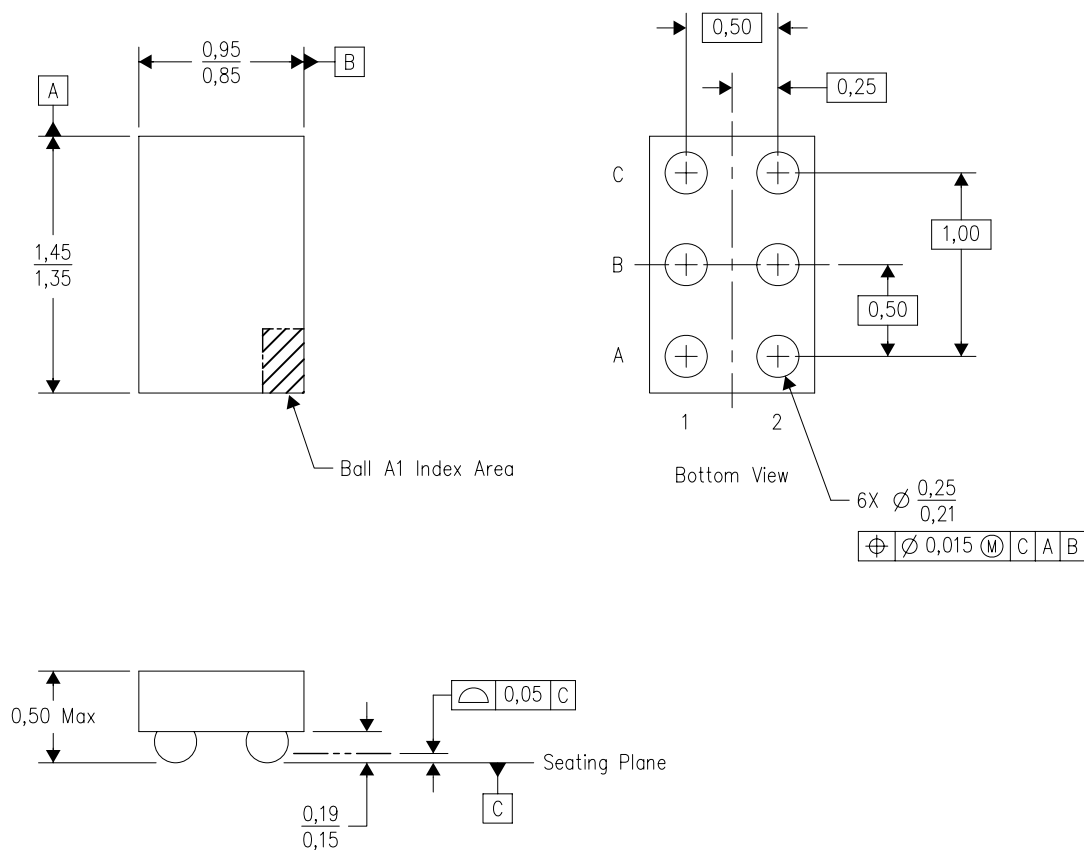


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G58DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0
SN74AUP1G58DBVT	SOT-23	DBV	6	250	202.0	201.0	28.0
SN74AUP1G58DCKR	SC70	DCK	6	3000	202.0	201.0	28.0
SN74AUP1G58DCKT	SC70	DCK	6	250	202.0	201.0	28.0
SN74AUP1G58DRLR	SOT	DRL	6	4000	202.0	201.0	28.0
SN74AUP1G58YZPR	DSBGA	YZP	6	3000	220.0	220.0	34.0

YZP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



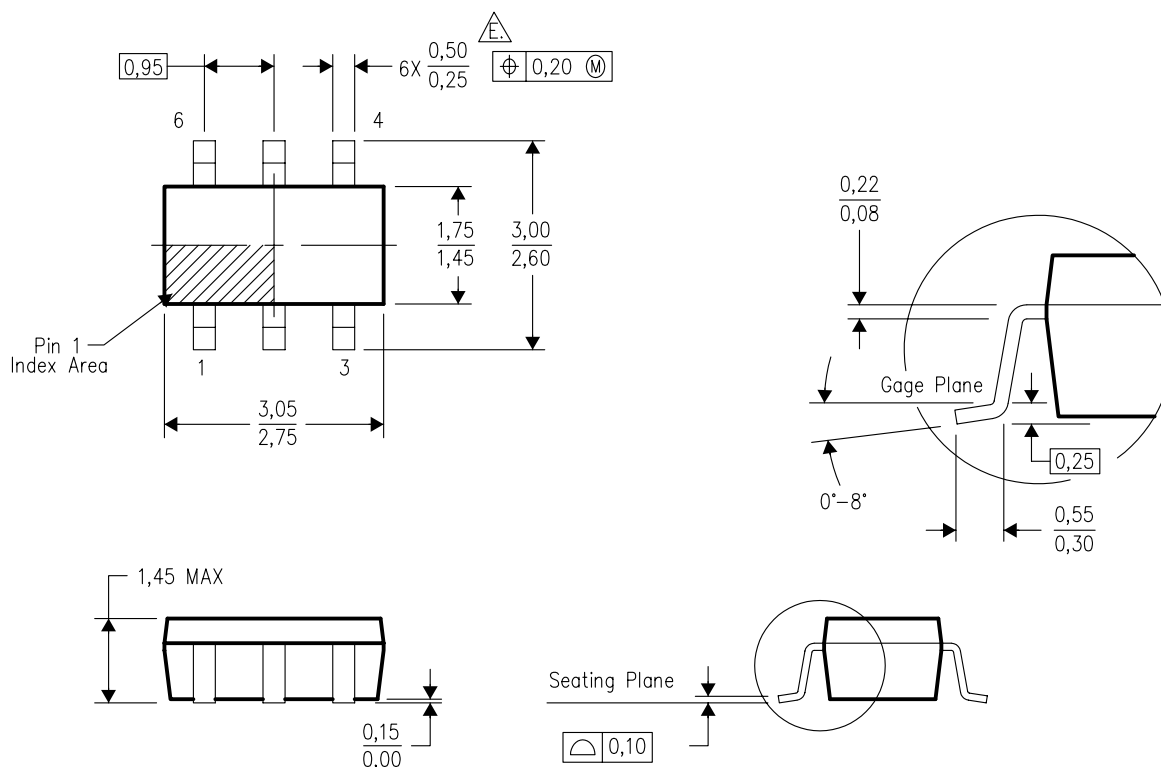
4204741-3/G 07/2008

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. This package is lead-free. Refer to the 6 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

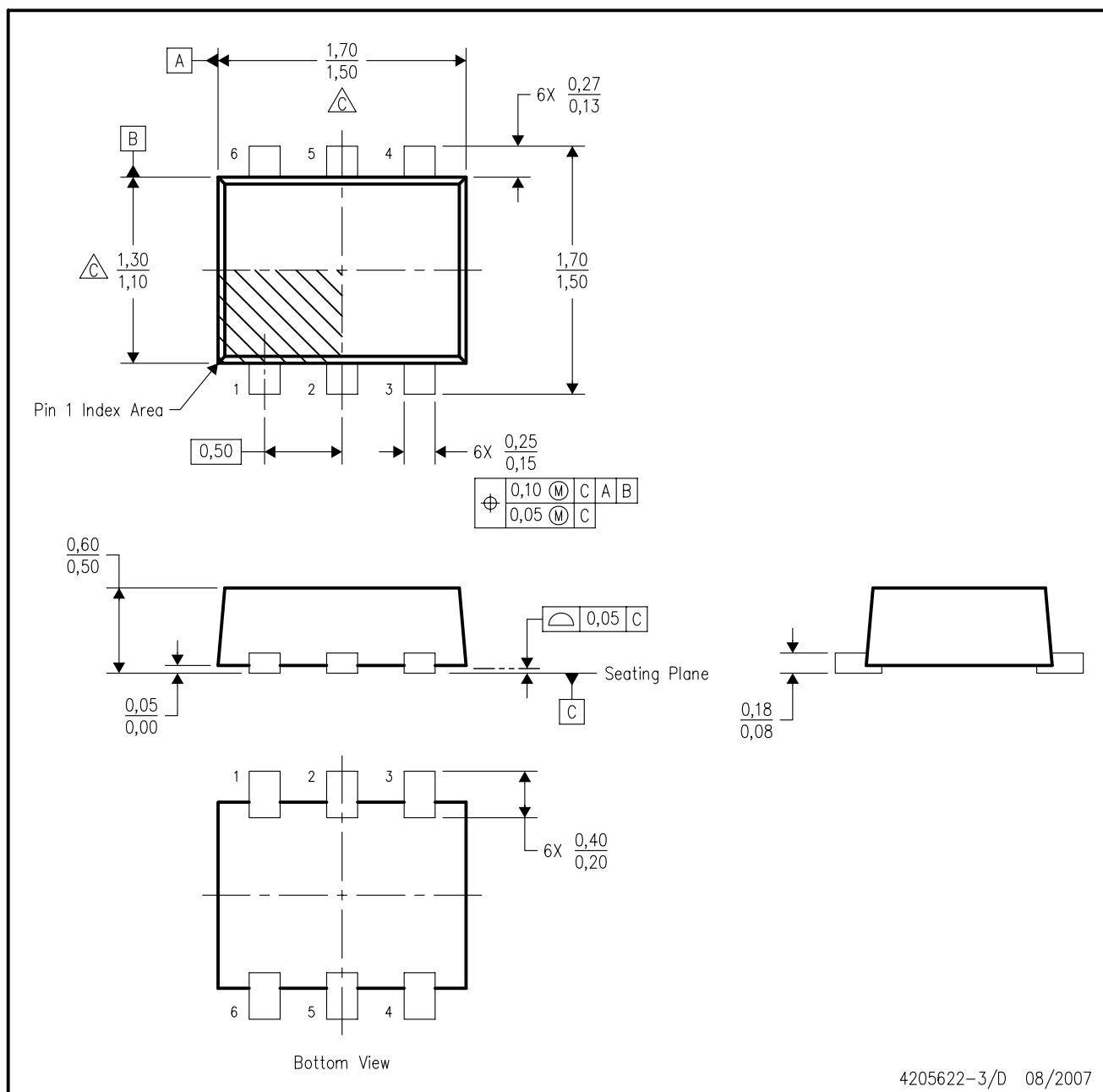



4073253-5/K 03/2006

NOTES:

- A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
E. Falls within JEDEC MO-178 Variation AB, except minimum lead width.

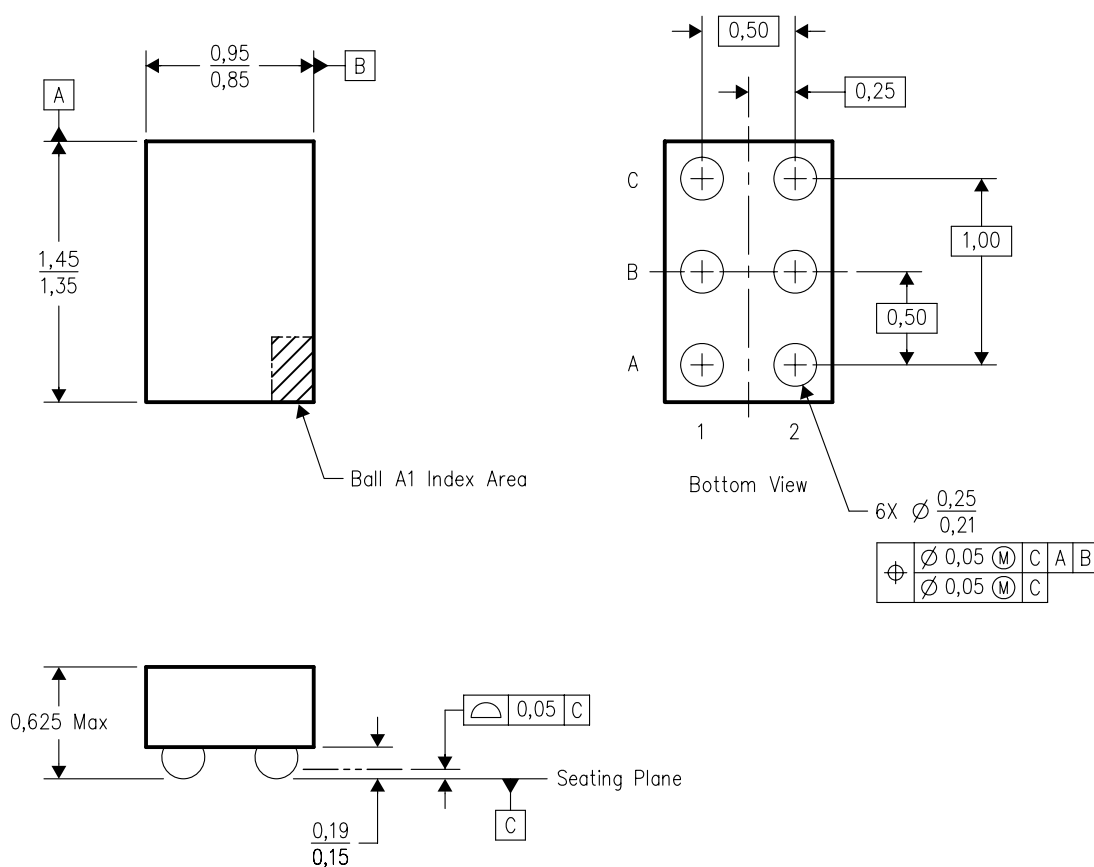
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
 - D. JEDEC package registration is pending.

YZT (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



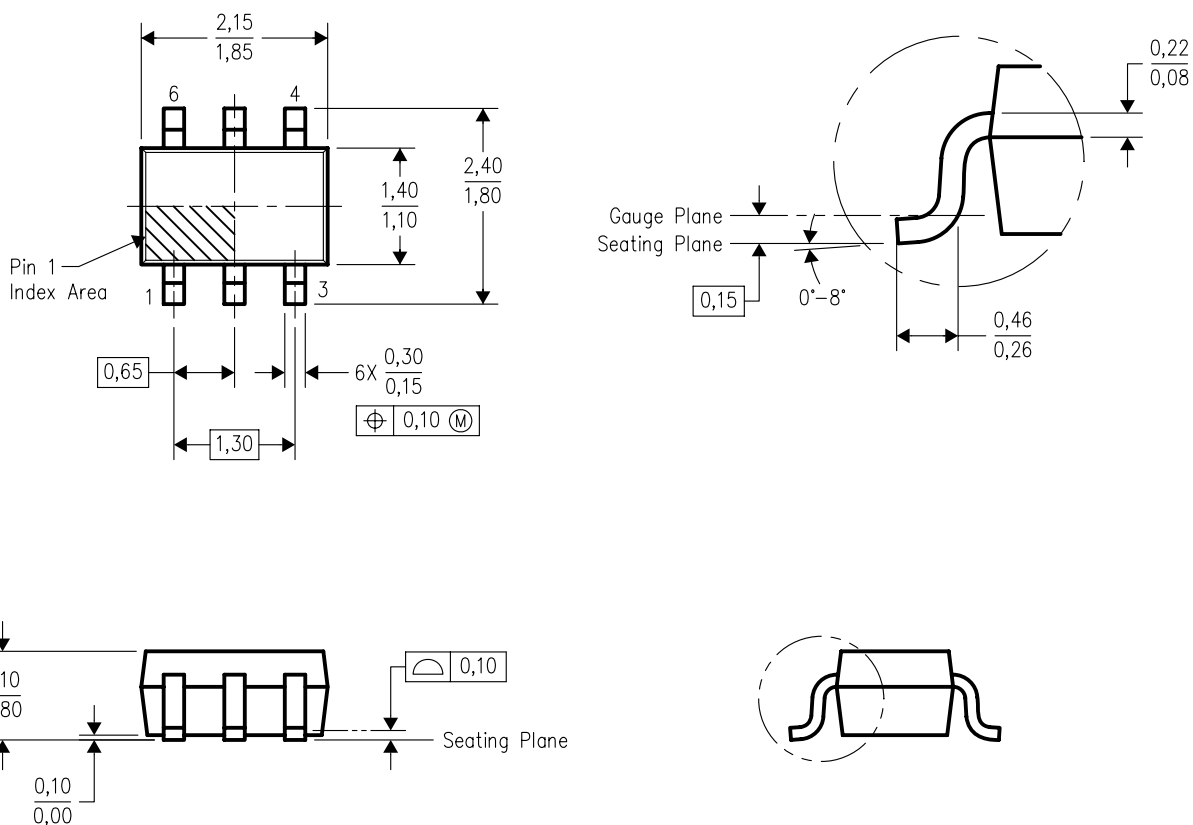
4205418-4/F 10/2006

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - NanoFree™ package configuration.
 - This package is Lead-free. Refer to the 6 YET package (drawing 4205421) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



4093553-4/G 01/2007

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-203 variation AB.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated